



May 18, 2009

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/786,807 Feb. 25, 2004

H. M. CHEN ET AL.

"METHOD FOR IMPROVING SEMICONDUCTOR  
WAFER TEST ACCURACY"

Grp. Art Unit: 2822

AU, BAC H

### RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action mailed Feb. 18, 2009, please amend the above-identified application for patent and consider the remarks, as follows:

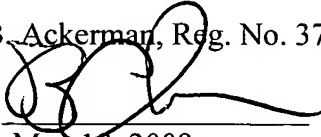
### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 18, 2009.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

  
May 18, 2009

**Amendments to the Claims** are reflected in the listing of the Claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.